

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: T.R. Cundiff et al. Attorney Docket No.: BOCO122200
Application No.: 10/758,404 Art Unit: 1762 / Confirmation No: 6099
Filed: January 15, 2004 Examiner: C.I. Sellman
Title: RESIN TRANSFER MOLDING PROCESS

COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Seattle, Washington 98101

October 31, 2006

TO THE COMMISSIONER FOR PATENTS:

Applicants acknowledge the allowance of Claims 1-8 in the subject application by the Examiner with appreciation. The applicants agree with the Examiner's Statement of Reasons for Allowance to the extent that the claims of the present invention are patentable over the references of record. The applicants expressly traverse the Examiners' Statement of Reasons for Allowance to the extent that any comment is intended or has the effect of limiting a claim scope, explicitly or implicitly, by not reciting verbatim the respective claim language, or is intended or has the effect of limiting a claim scope by stating or implying that all the reasons for patentability are in any way fully enumerated.

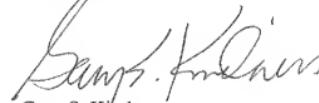
Applicants further point out that the reasons for allowance set forth by the Examiner are not the only reasons that the claims are allowable. Further reasons for allowance of the claims beyond those enumerated by the Examiner are described and set forth in the file. In addition,

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structures and methods that perform substantially the same function in substantially the same way to achieve substantially the same results are included within the scope of the claims.

Respectfully submitted,

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